Revision Record					
Control No.	**Revision**	**Description**	**Date**	**Drawn**	**Approved**
					Roger
					Roger
					Roger
					Roger

TDG HOLDING CO., LTD.

TMAX-1350-XXX-M Molded Power Inductor

Features

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Applications

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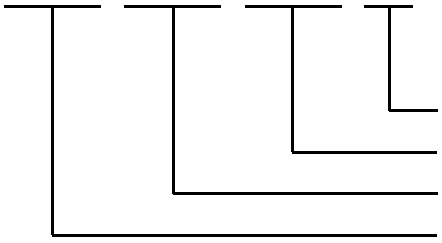
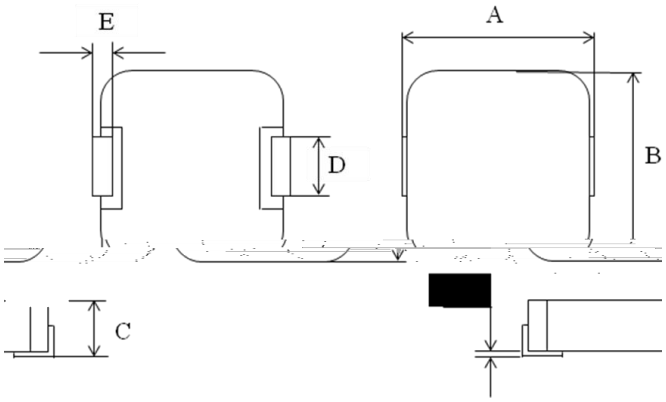
Product Description

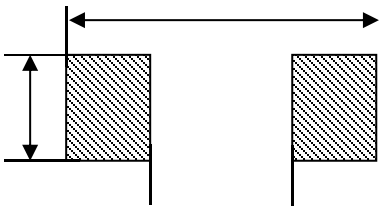


Dimensions

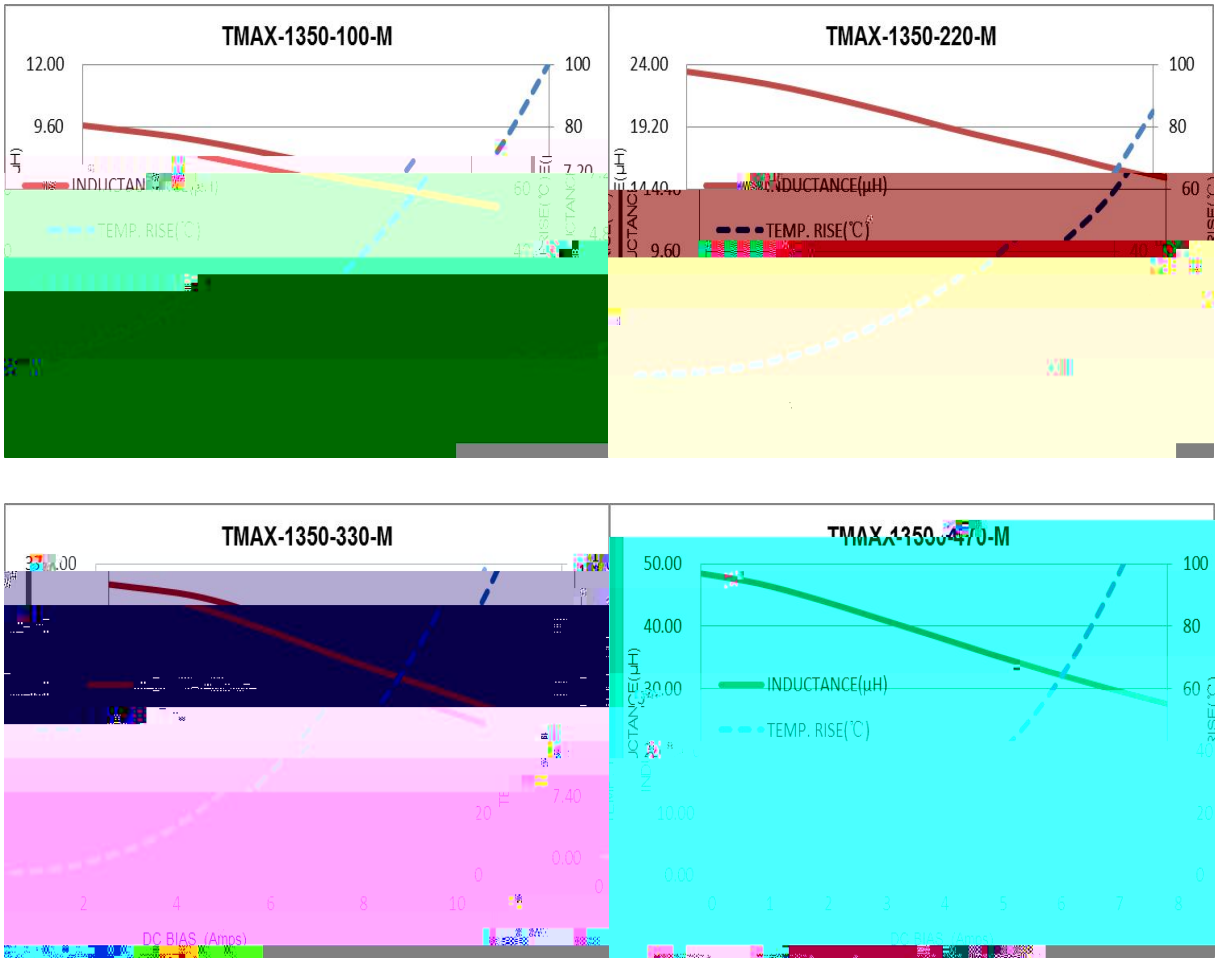


	R68	4R7~470
	13.8Max	
	12.7±0.2	
	5.0 Max.	
	3.7±0.5	5.0±0.5
	2.3±0.5	
	0~0.20	

Recommend Land Pattern Dimensions



Notes:


TMAX-1350-100-M
12.00
9.60
100
80
INDUCTANCE(μH)
TEMP. RISE(℃)
TMAX-1350-220-M
24.00
19.20
14.40
9.60
100
80
60
INDUCTANCE(μH)
TEMP. RISE(℃)
TMAX-1350-330-M
DC BIAS (Amps)
TMAX-1350-470-M
50.00
40.00
30.00
100
80
60
INDUCTANCE(μH)
TEMP. RISE(℃)

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Reliability:

Item	Test Method	Specification and Requirement

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Peeling of top cover tape

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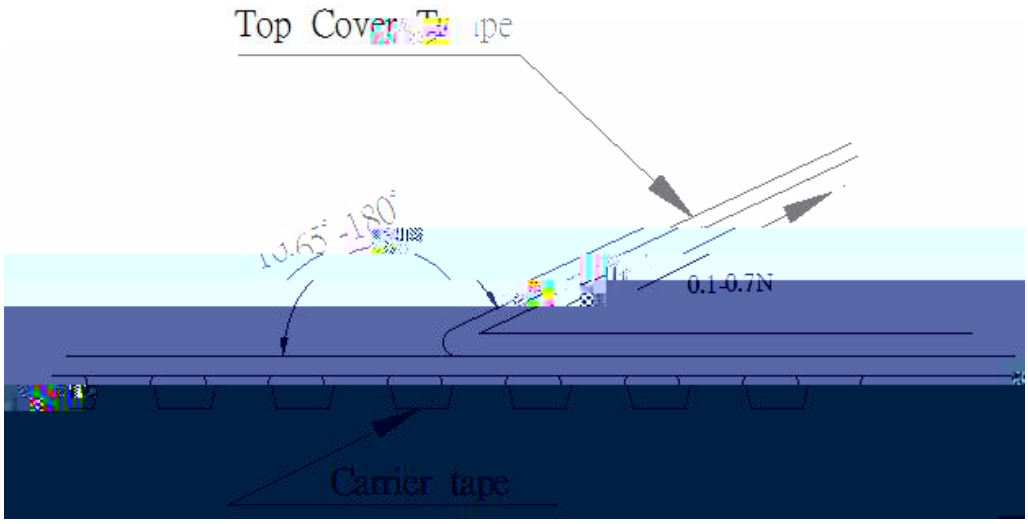

Reflow Profile

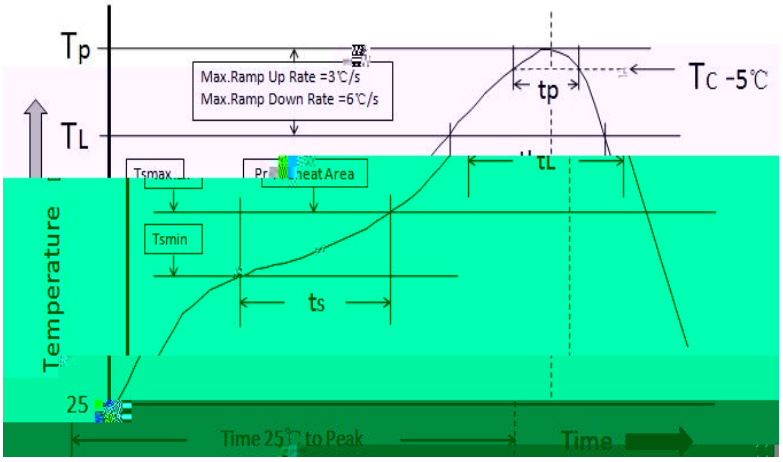

Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm^3 350	Volume mm^3 350

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm^3 350	Volume mm^3 350-2000	Volume mm^3 >2000

Reference JDEC J-STD-020(latest revision)

Profile Feature		Standard SnPb solder	Lead(Pb) Free Solder

Numbers of taping

●

Label marking

●

●

Production Label	Shipping Label
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓

Care note for Safety

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